

description (continued)

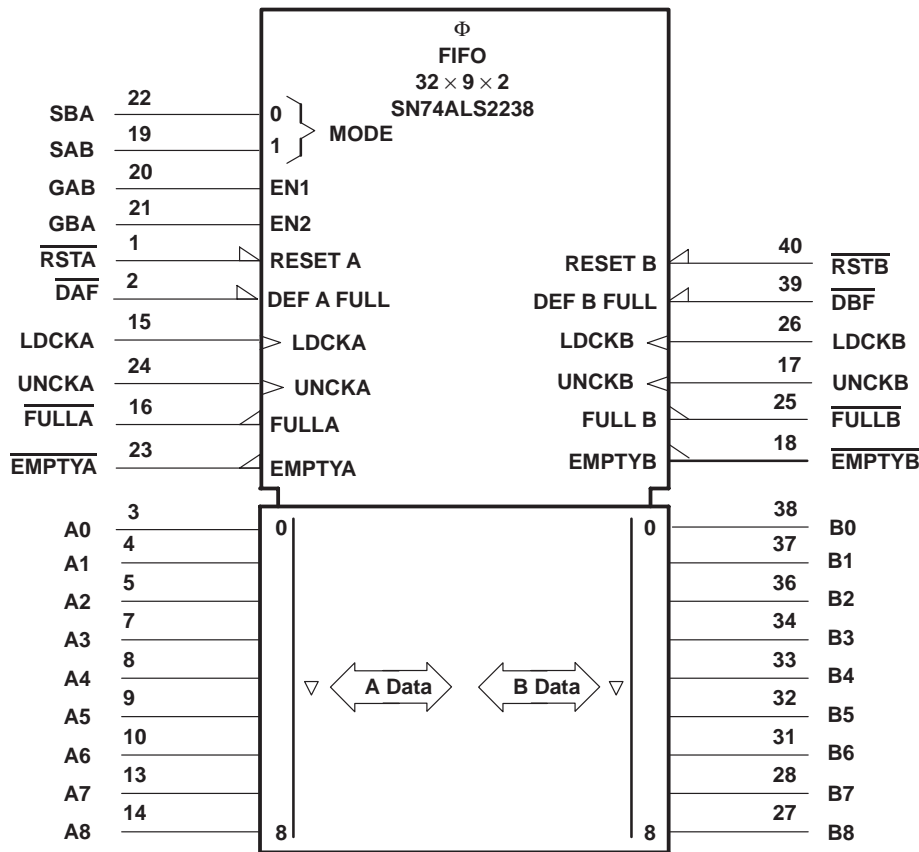
Status of the FIFO memories is monitored by the \overline{FULLA} , \overline{FULLB} , \overline{EMPTYA} , and \overline{EMPTYB} output flags. The \overline{FULLA} and \overline{FULLB} are definable full flags. A high-to-low transition on \overline{DAF} stores the binary value of A0 through A4 into a register for use as the value of X. A high-to-low transition on \overline{DBF} stores the binary value of B0 through B4 into a register for use as the value of Y. In this way, the depth of either FIFO can be defined to be one to 32 words deep. The value of X and Y must be defined after power up or the stored value of X and Y will be ambiguous. The \overline{FULLA} and \overline{FULLB} outputs are low when their corresponding memories are full and high when the memories are not full.

The \overline{EMPTYA} and \overline{EMPTYB} outputs are low when their corresponding memories are empty and high when they are not empty. The status flag outputs are always active.

A low-level pulse on the \overline{RSTA} or \overline{RSTB} inputs resets the control pointers on FIFO A or FIFO B and also sets \overline{EMPTYA} low and \overline{FULLA} high or \overline{EMPTYB} low and \overline{FULLB} high. The outputs are not reset to any specific logic levels. With \overline{DAF} at a low level, a low-level pulse on \overline{RSTA} sets FIFO A to a depth of 32 – X, where X is the value stored above. With \overline{DAF} at a high level, a low level pulse on \overline{RSTA} sets FIFO A to a depth of 32 words. The depth of FIFO B is set in a similar manner. The first low-to-high transition on LDCKA or LDCKB, either after a reset pulse or from an empty condition, will cause \overline{EMPTYA} or \overline{EMPTYB} to go high and the data to appear on the Q outputs. It is important to note that the first word does not have to be unloaded. Cascading is easily accomplished in the word-width direction, but is not possible in the word-depth direction.

The SN74ALS2238 is characterized for operation from 0°C to 70°C.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the N package.

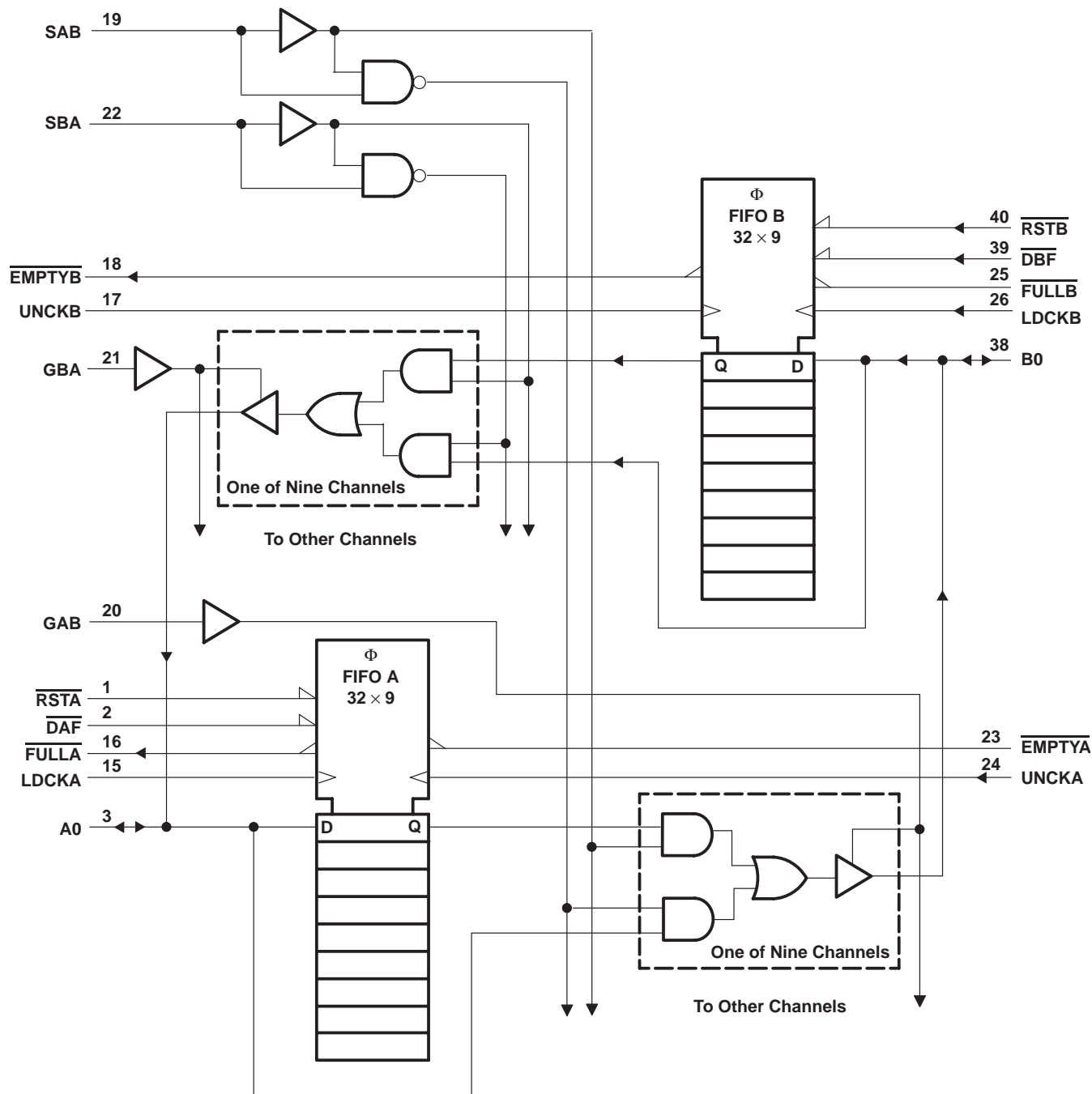


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logic diagram (positive logic)



Pin numbers shown are for the N package.



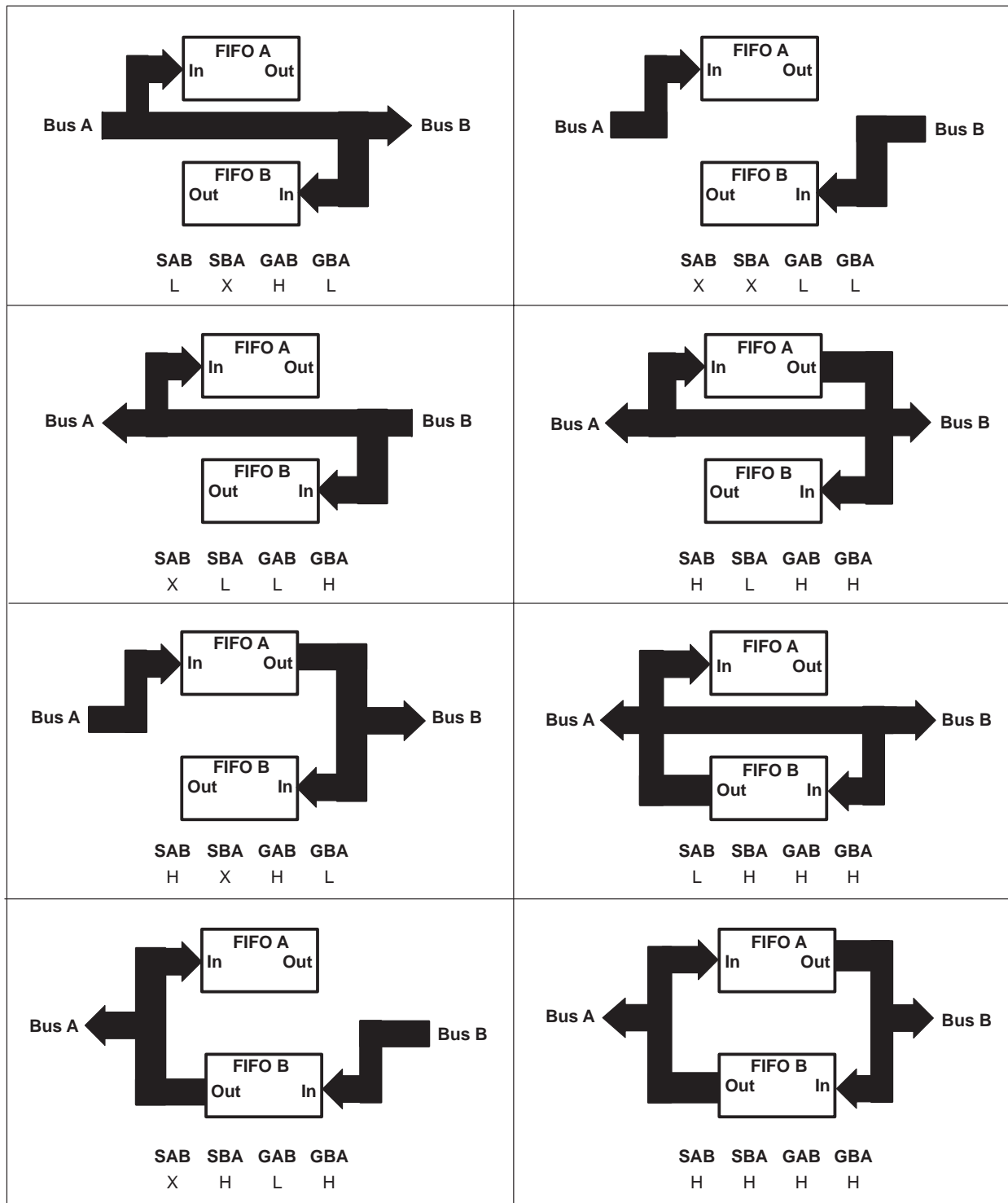
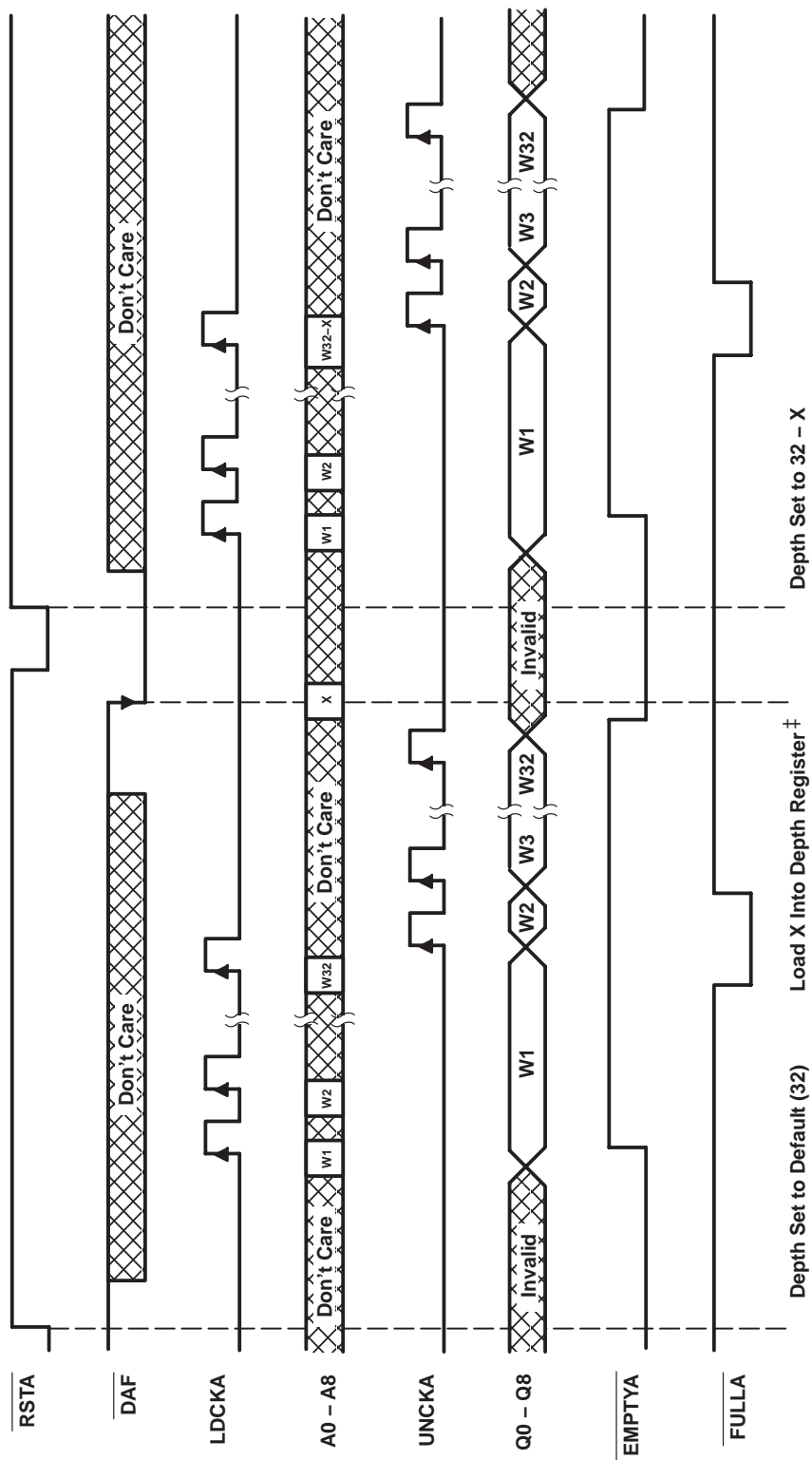


Figure 1. Bus-Management Functions

timing diagram for FIFO A†



† Operation of FIFO B is identical to that of FIFO A.

‡ X includes A0 through A4 only. A5 through A8 are ignored.

SELECT-MODE CONTROL TABLE

CONTROL		OPERATION	
SAB	SBA	A BUS	B BUS
L	L	Real-time B to A bus	Real-time A to B bus
L	H	FIFO B to A bus	Real-time A to B bus
H	L	Real-time B to A bus	FIFO A to B bus
H	H	FIFO B to A bus	FIFO A to B bus

OUTPUT-ENABLE CONTROL TABLE

CONTROL		OPERATION	
GAB	GBA	A BUS	B BUS
H	H	A bus enabled	B bus enabled
L	H	A bus enabled	Isolation/input to B bus
H	L	Isolation/input to A bus	B bus enabled
L	L	Isolation/input to A bus	Isolation/input to B bus

programming procedure for depth of FIFO A†

Program:

- Step 1. With \overline{RSTA} at a high level, take \overline{DAF} from a high level to a low level. The high-to-low transition on \overline{DAF} stores the binary value of A0–A4 for use as the value of X in defining the depth of FIFO A.
- Step 2. With \overline{DAF} held low, pulse the \overline{RSTA} signal low. On the low-to-high transition of \overline{RSTA} , FIFO A is set to a depth of 32 – X, where X is the value of A0–A4 stored above.
- Step 3. To redefine the depth of FIFO A to 32 words, hold \overline{DAF} at a high level and pulse the \overline{RSTA} signal low.

† The programming procedures used to define the depth of FIFO B are the same as the procedure above.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC}	–0.5 V to 7 V
Input voltage: Control inputs	7 V
I/O ports	5.5 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range	–65°C to 150°C
Maximum junction temperature	150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



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recommended operating conditions (see Note 1)

		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
I _{OH}	High-level output current	A or B ports		-15	mA
		Status flags		-0.4	
I _{OL}	Low-level output current	A or B ports		24	mA
		Status flags		8	
f _{clock}	Clock frequency	LDCKA or LDCKB		0	MHz
		UNCKA or UNCKB		0	
t _w	Pulse duration	\overline{RSTA} or \overline{RSTB} low		17	ns
		LDCKA or LDCKB low		12.5	
		LDCKA or LDCKB high		10	
		UNCKA or UNCKB low		12.5	
		UNCKA or UNCKB high		10	
		\overline{DAF} or \overline{DBF} high		10	
t _{su}	Setup time	Data before LDCKA or LDCKB \uparrow		7	ns
		Define depth: D4 – D0 before \overline{DAF} or $\overline{DBF}\downarrow$		6	
		Define depth: \overline{DAF} or $\overline{DBF}\downarrow$ before \overline{RSTA} or $\overline{RSTB}\uparrow$		45	
		Define depth (32): \overline{DAF} or \overline{DBF} high before \overline{RSTA} or $\overline{RSTB}\uparrow$		32	
		LDCKA or LDCKB (inactive) before \overline{RSTA} or $\overline{RSTB}\uparrow$		5	
t _h	Hold time	Data after LDCKA or LDCKB \uparrow		3	ns
		Define depth: D4 – D0 after \overline{DAF} or $\overline{DBF}\downarrow$		4	
		Define depth: \overline{DAF} or \overline{DBF} low after \overline{RSTA} or $\overline{RSTB}\uparrow$		0	
		Define depth (32): \overline{DAF} or \overline{DBF} high after \overline{RSTA} or $\overline{RSTB}\uparrow$		0	
		LDCKA or LDCKB (inactive) after \overline{RSTA} or $\overline{RSTB}\uparrow$		5	
T _A	Operating free-air temperature	0		70	°C

NOTE 1: To ensure proper operation of this high-speed FIFO device, it is necessary to provide a clean signal to the LDCKA or LDCKB and UNCKA or UNCKB clock inputs. Any excessive noise or glitching on the clock inputs (which violates the V_{IL}, V_{IH}, or minimum pulse duration limits) can cause a false clock or improper operation of the internal read and write pointers.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V, I _I = -18 mA			-1.2	V
V _{OH}	Status flags	V _{CC} = 4.5 V to 5.5 V, I _{OH} = -0.4 mA	V _{CC} -2			V
	A or B ports	V _{CC} = 4.5 V, I _{OH} = -2 mA	V _{CC} -2			
		V _{CC} = 4.5 V, I _{OH} = -3 mA	2.4	3.2		
		V _{CC} = 4.5 V, I _{OH} = -15 mA	2			
V _{OL}	A or B ports	V _{CC} = 4.5 V, I _{OL} = 12 mA	0.25	0.4		V
		V _{CC} = 4.5 V, I _{OL} = 24 mA	0.35	0.5		
	Status flags	V _{CC} = 4.5 V, I _{OL} = 4 mA	0.25	0.4		
		V _{CC} = 4.5 V, I _{OL} = 8 mA	0.35	0.5		
I _I	DAF, DBF, RSTA, RSTB, GAB, GBA, SAB, SBA, LDCKA, LDCKB, UNCKA, UNCKB	V _{CC} = 5.5 V, V _I = 7 V			0.1	mA
	A or B ports				0.2	
I _{IH}	DAF, DBF, RSTA, RSTB, GAB, GBA, SAB, SBA, LDCKA, LDCKB, UNCKA, UNCKB	V _{CC} = 5.5 V, V _I = 2.7 V			20	μA
	A or B ports‡				40	
I _{IL}	DAF, DBF, RSTA, RSTB, GAB, GBA, SAB, SBA, LCKA, LDCKB, UNCKA, UNCKB	V _{CC} = 5.5 V, V _I = 0.4 V			-0.2	mA
	A or B ports‡				-0.4	
I _O §	A or B ports‡	V _{CC} = 5.5 V, V _O = 2.25 V	-20		-130	mA
	Status flags		-15		-100	
I _{CC}		V _{CC} = 5.5 V		190	350	mA

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ For I/O ports, the parameters I_{IH} and I_{IL} include the offstate output current.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.



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switching characteristics over recommended ranges of supply voltage and operating free-air temperature (see Figure 2)

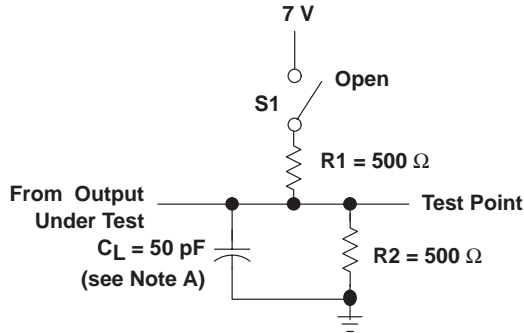
PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L = 50 pF, R ₁ = 500 Ω, R ₂ = 500 Ω			UNIT
			MIN	TYP†	MAX	
f _{max}	LDCK, UNCK		40			MHz
t _{pd}	LDCKA↑, LDCKB↑	B, A	7	22	33	ns
	UNCKA↑, UNCKB↑		7	20	29	
t _{PLH}	LDCKA↑, LDCKB↑	$\overline{\text{EMPTYA}}, \overline{\text{EMPTYB}}$	5	12	22	ns
t _{PHL}	UNCKA↑, UNCKB↑		5	12	22	
t _{PHL}	$\overline{\text{RSTA}}\downarrow, \overline{\text{RSTB}}\downarrow$	$\overline{\text{EMPTYA}}, \overline{\text{EMPTYB}}$	5	12	22	ns
t _{PHL}	LDCKA↑, LDCKB↑	$\overline{\text{FULLA}}, \overline{\text{FULLB}}$	5	12	22	ns
t _{PLH}	UNCKA↑, UNCKB↑	$\overline{\text{FULLA}}, \overline{\text{FULLB}}$	5	12	23	ns
	$\overline{\text{RSTA}}\downarrow, \overline{\text{RSTB}}\downarrow$		6	15	28	
t _{pd}	SAB, SBA‡	B, A	2	11	18	ns
	A/B		2	8	15	
t _{en}	GBA, GAB	A, B	2	6	15	ns
t _{dis}	GBA, GAB	A, B	1	5	12	ns

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ These parameters are measured with the internal output state of the storage register opposite to that of the bus input.



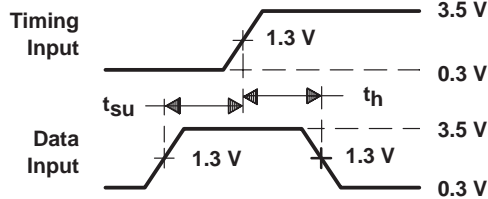
PARAMETER MEASUREMENT INFORMATION



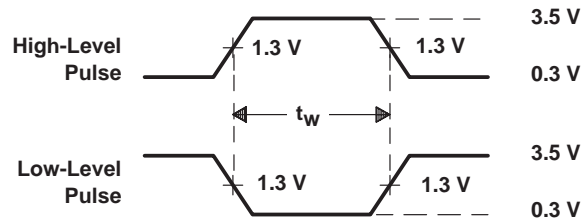
LOAD CIRCUIT FOR 3-STATE OUTPUTS

SWITCH POSITION TABLE

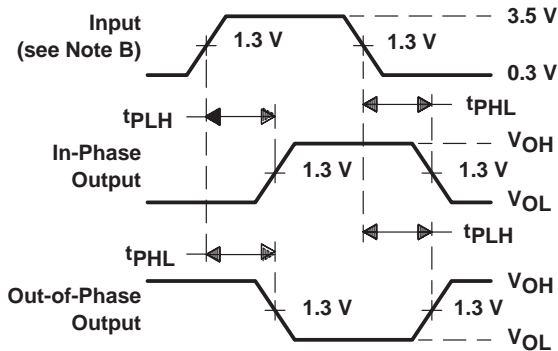
TEST	S1
t _{PLH}	Open
t _{PHL}	Open
t _{PZH}	Open
t _{PZL}	Closed
t _{PHZ}	Open
t _{PLZ}	Closed



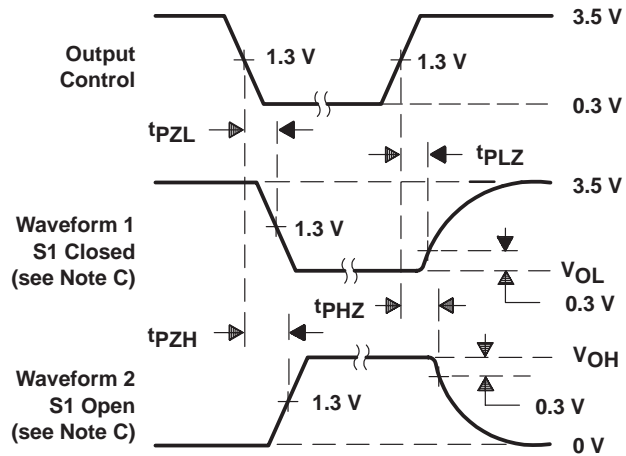
VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- NOTES: A. C_L includes probe and jig capacitance.
 B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_0 = 50 \Omega$, $t_r \leq 2$ ns, $t_f \leq 2$ ns.
 C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

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